

SIMULATION WG MEETING 28.4.2015

STATUS AT HELSINKI

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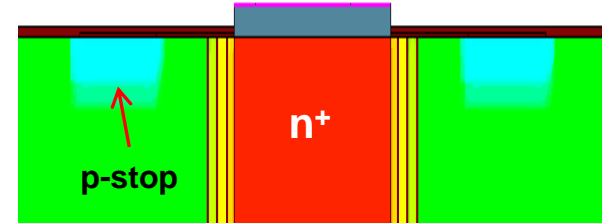
Outline

- 3D columnar detector transient & CV/IV simulations: $\Phi_{eq} = 1e16 \text{ cm}^{-2}$**
- Phase II pixels: charge sharing at 400 V (simplified structure)**

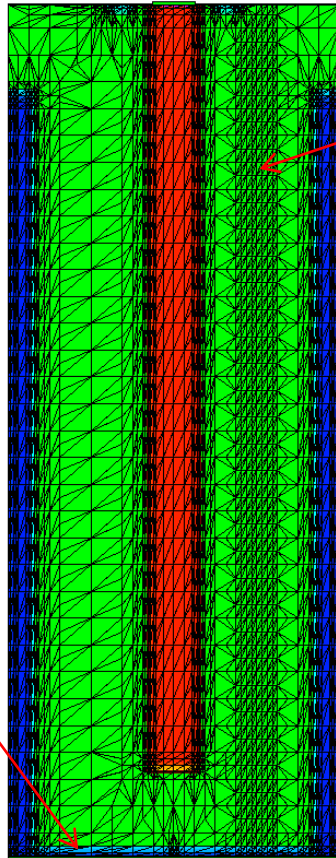
Double type column 3D-sensor simulations: structure

- ❑ **Double-side double type column 3D-sensor structure**
- ❑ 55x55x200 μm^3 structure, 250 nm oxide layer & 500 nm Al on both planes
- ❑ P-type bulk with 180 μm n^+/p^+ columns ($r = 5 \mu\text{m}$)
- ❑ All p^+ contacts connected together by the backplane Al
- ❑ p-stop depth = 1.5 μm , $r_{\text{in}} = 10 \mu\text{m}$, $r_{\text{out}} = 15 \mu\text{m}$

DC-coupled front contact ($R_{\text{bias}} = 50 \Omega$)



Diagonal cut

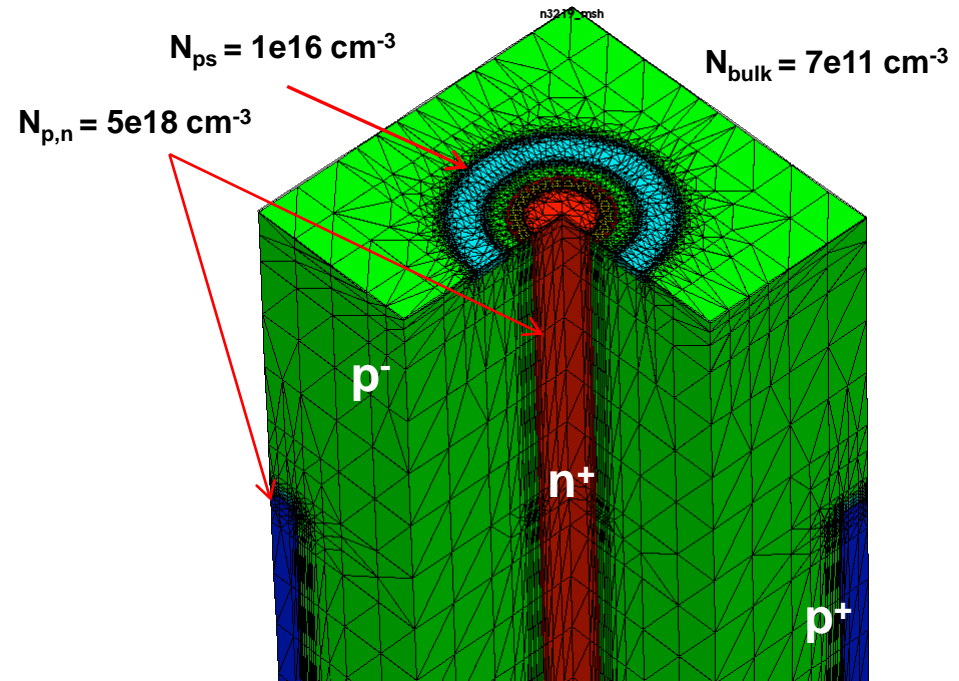


- ❑ Reduced mesh size around MIP trajectory

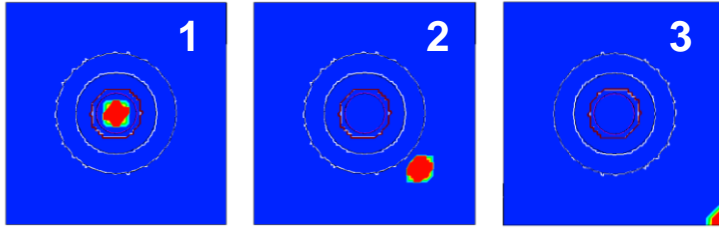
- ❑ 29 615 mesh points (> 30 k: memory allocation crash)
- ❑ Column doping profiles by error function

- ❑ p^+ doping at backplane to reduce low field region

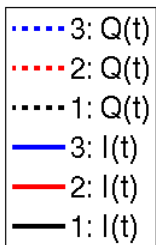
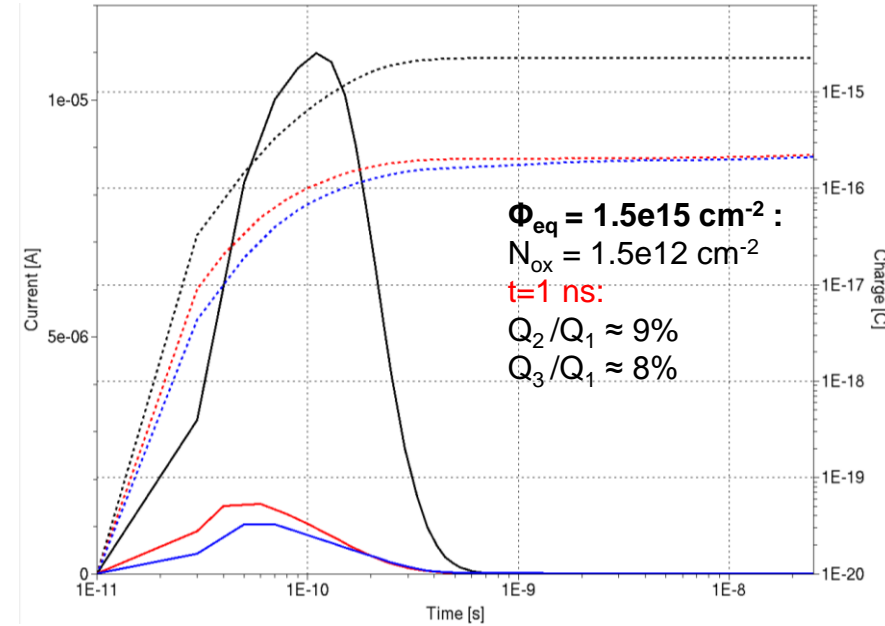
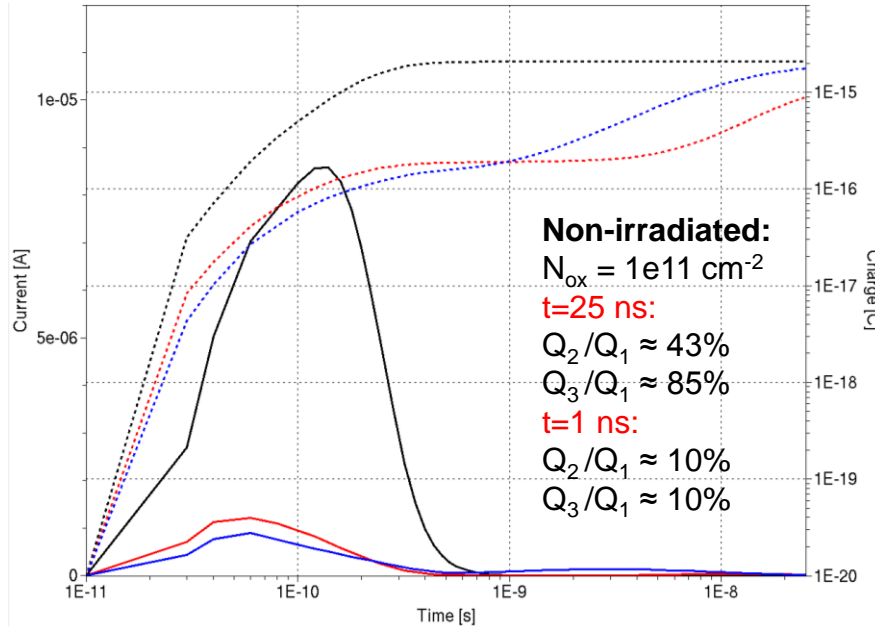
Doping profiles
(Oxide layer transparent for clarity)



3D transient simulations: non-irradiated & protons



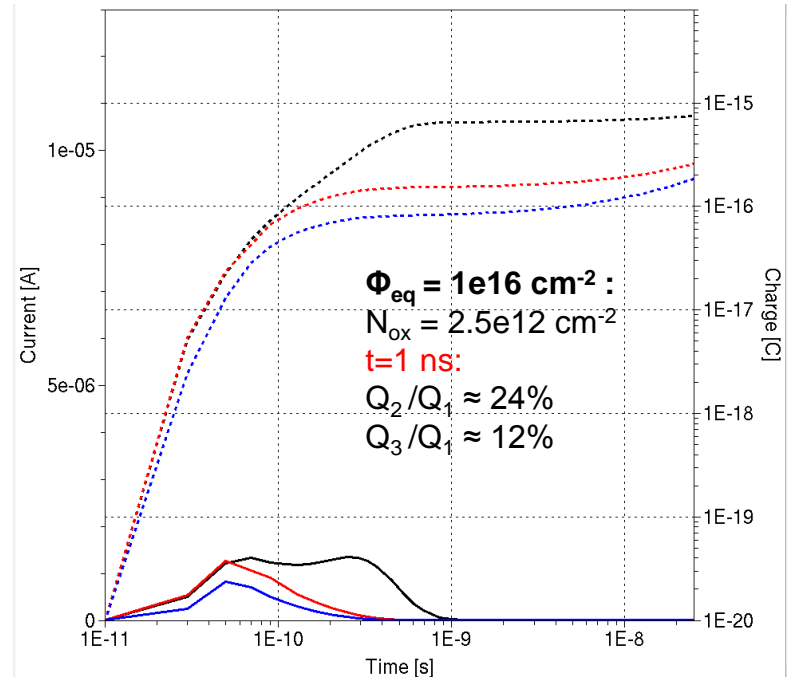
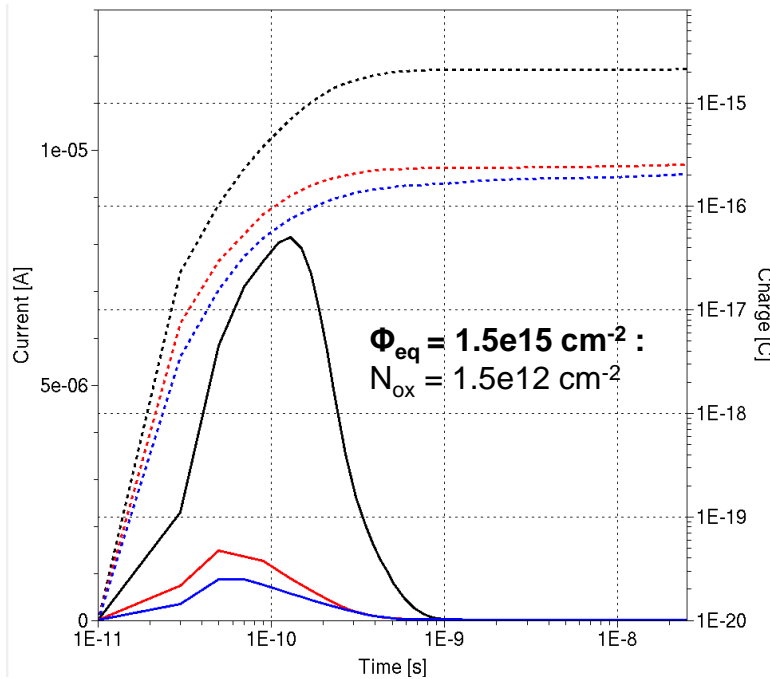
- Hit position 1: n+ column (hole transient)
- Hit position 2: midgap (electron + hole transient)
- Hit position 3: p+ column (electron transient)
- V=-100 V, T=253 K (non-irradiated: T=293 K), MIP $\sigma = 0.5 \mu\text{m}$
- DC-coupled contacts: $R_{\text{front}} = R_{\text{back}} = 50 \Omega$



Defects

- **Bulk:** proton model
- **Within $2 \mu\text{m}$ of surface:** proton model + shallow acceptors
= non-uniform 3-level model

3D transient simulations: high Φ @ V=40 V



-3: Q(t)
-2: Q(t)
-1: Q(t)
-3: I(t)
-2: I(t)
-1: I(t)

□ Essentially no voltage dependence between 40 V – 100 V for $\Phi_{eq} = 1.5e15 \text{ cm}^{-2}$

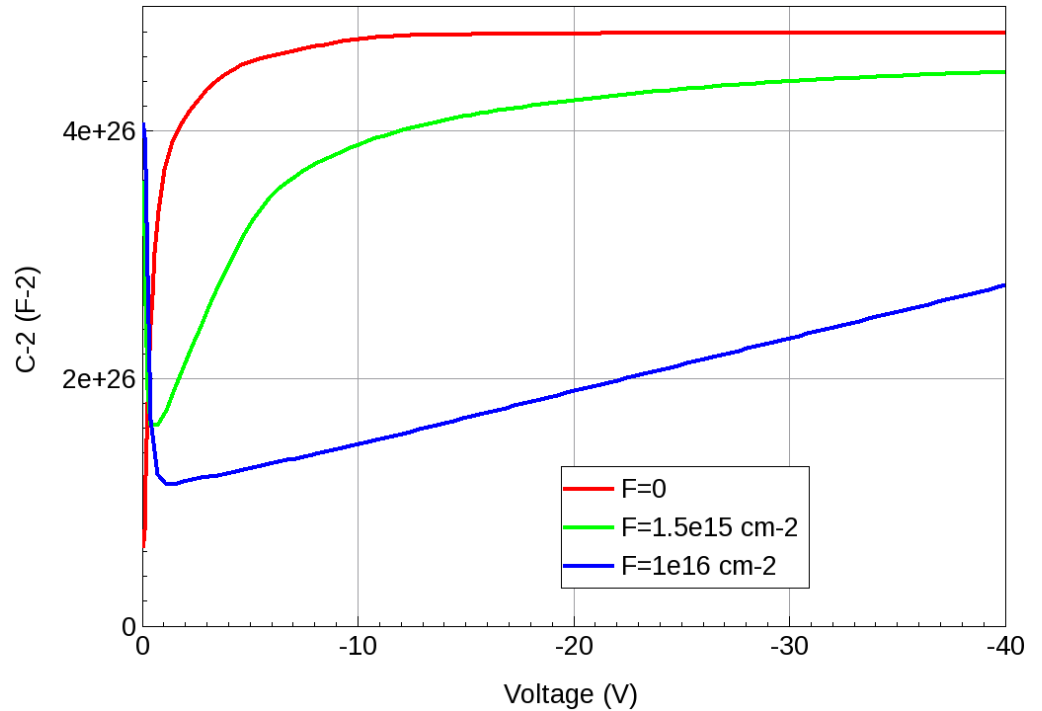
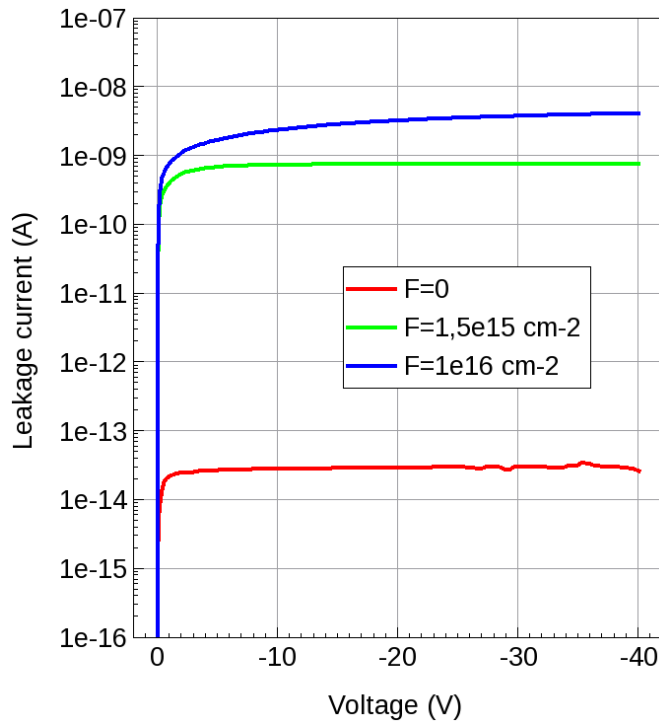
□ **Position 2 (midgap) most radiation hard:** $\frac{1}{2}$ of max. drift distance between electrodes

□ **Position 1 (n+): Pros:** high E region, **Cons:** transient from holes

□ **Position 3 (p+): Pros:** transient from electrons, **Cons:** low E region

Hit position	Fluence [cm^{-2}]	CCE @ 1 ns [%]
1	1.5e15	100
2	1.5e15	100
3	1.5e15	90
1	1e16	34
2	1e16	85
3	1e16	42

3D CV/IV simulations: high Φ @ V=40 V

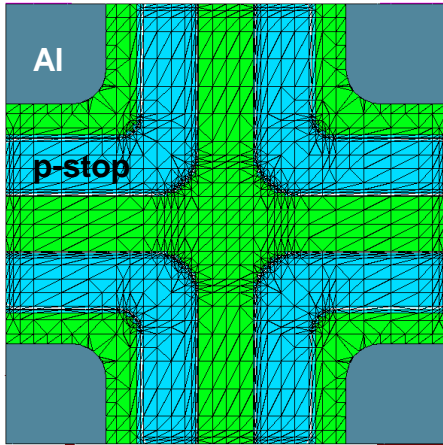


α (253K) = $8.9 \cdot 10^{-19}$ A·cm⁻¹
 $I = V \cdot \alpha \cdot \Phi$
 $\rightarrow I(1.5e15) \approx 0.8$ nA
 $I(1e16) \approx 5.4$ nA

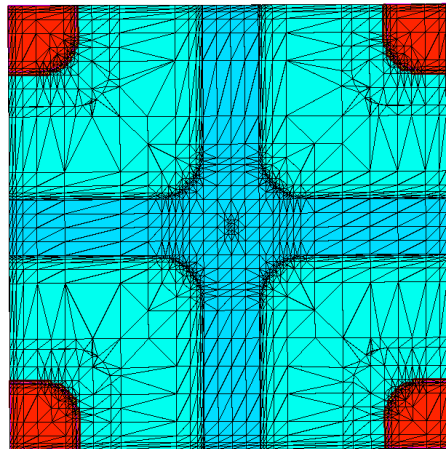
- Irradiated LC agrees with experimental also @ $\Phi_{eq} = 1e16$ cm⁻²
- $\Phi_{eq} = 1e16$ cm⁻²: Sensor not fully depleted @ V=40 V

Phase II pixel: Corner region structure

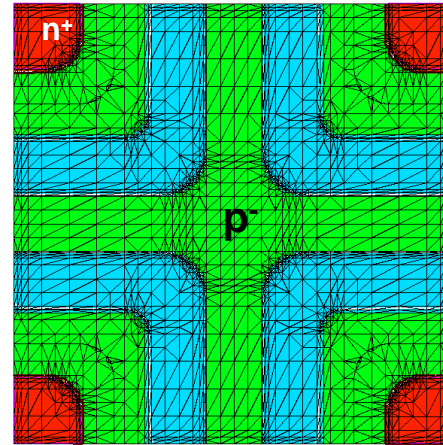
Normal: P-stop with Al



Normal: P-spray & implants



Normal: P-stop & implants



$N_n = 1e19 \text{ cm}^{-3}$

Normal (N): $23/4 = 5.75$
Wide (W): $30/4 = 7.5$

N: 6.0

W: 5.0

N: 5.0

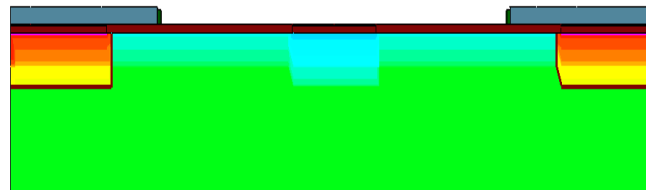
W: 3.0

N: 5.0

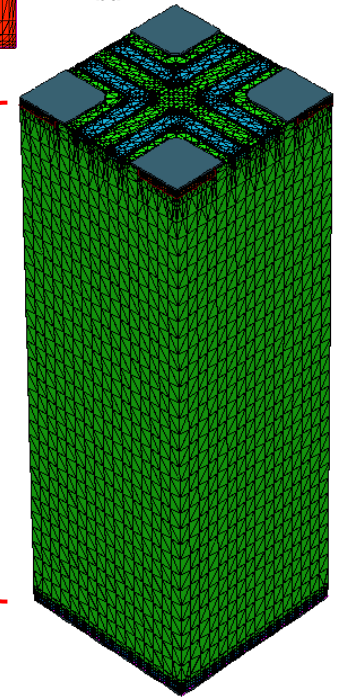
W: 4.0

$N_{\text{bulk}} = 1.68e12 \text{ cm}^{-3}$

$N_{\text{pstop}} = 5e16 \text{ cm}^{-3}$



150 μm



❑ **Corrected** moderate p-spray:

- Center: peak= $1e17 \text{ cm}^{-3}$, $d=1.5\mu\text{m}$
- Elsewhere: peak= $1e15 \text{ cm}^{-3}$, $d=1\mu\text{m}$

- ❑ Normal & wide designs, $MO = 3 \mu\text{m}$
- ❑ Minimized complexity: 'ideal' DC-coupling (no vias/punch throughs)
- ❑ Mesh points: from $\sim 30\text{k}$ to $\sim 106\text{k}$
- ❑ $\frac{1}{4}$ of implant included for corner region simulations to maximize mesh density

Normal vs wide: V_{bd} for p-bulk tuned lifetimes

□ Corrected moderated p-spray design
(single high concentration region)

□ $Q_f = 1e11 \text{ cm}^{-2}$

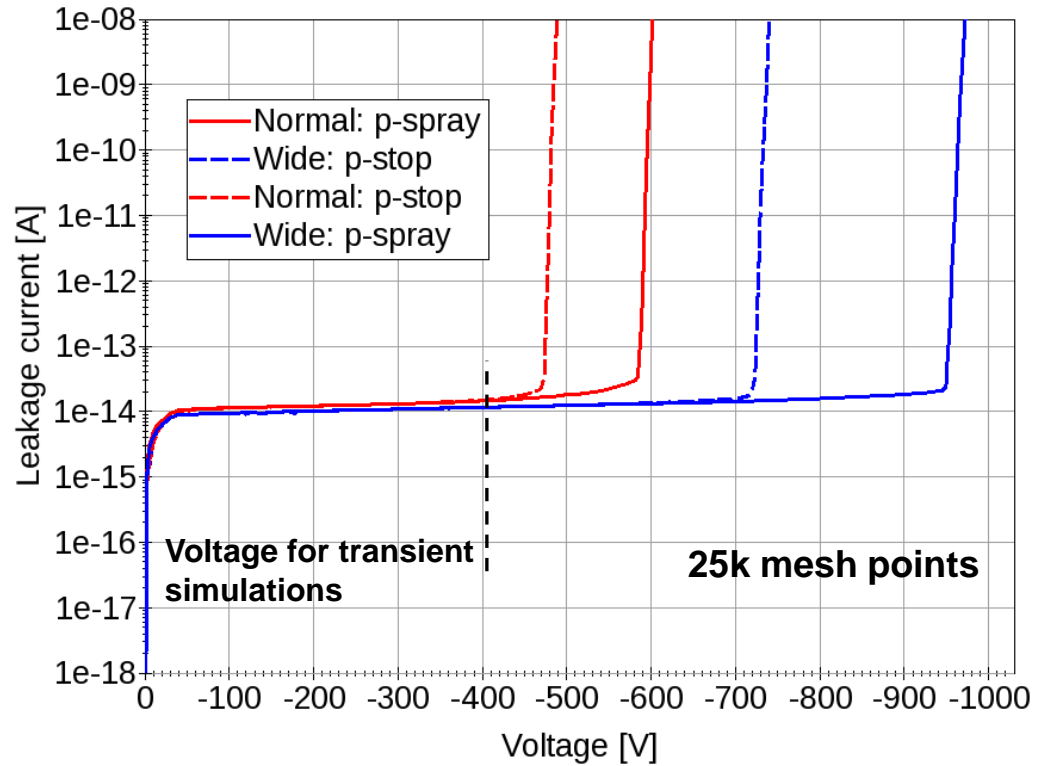
□ Tuned e & h lifetimes for p-bulk:

$\tau_e = 1e-2 \text{ s}$, $\tau_h = 1e-2 \text{ s}$

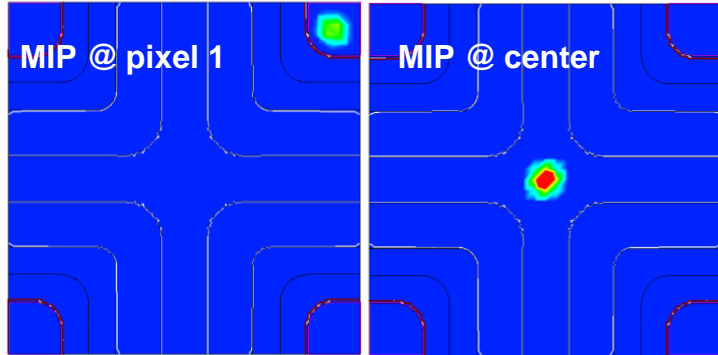
▪ **Normal:** $V_{bd}(\text{p-spray}) \approx 590 \text{ V}$, $V_{bd}(\text{p-stop}) \approx 470 \text{ V}$

▪ **Wide:** $V_{bd}(\text{p-spray}) \approx 950 \text{ V}$, $V_{bd}(\text{p-stop}) \approx 720 \text{ V}$

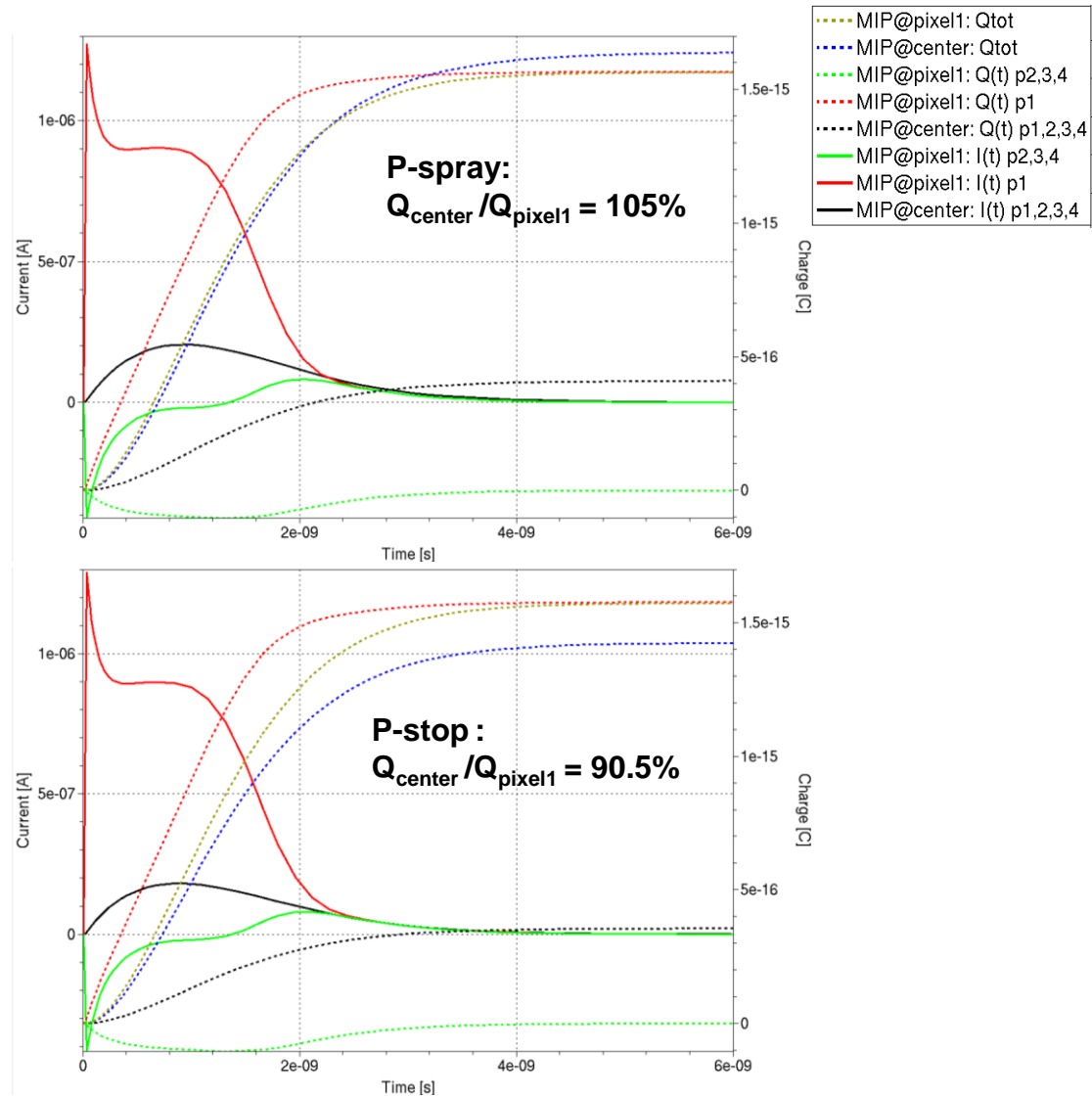
→ **superior V_{bd} for wide design with p-spray**



Transient simulations: charge sharing of 'Normal' design



- MIP injection at pixel 1 & center
- Non-irradiated, $V = -400\text{ V}$, $Q_f = 1e11\text{ cm}^{-2}$, $T = 293\text{ K}$
- MIP @ pixel 1:
 - Charge sharing = 0
- MIP @ center:
 - **P-spray**: higher cluster charge than for MIP @ pixel 1!
 - **Charge loss >10% higher for p-stop** with $N_{ps} = 5e16\text{ cm}^{-3}$, $d=1.5\text{ }\mu\text{m}$



Transient simulations: charge sharing of 'Wide' design

- ❑ MIP injection at pixel 1 & center
- ❑ Non-irradiated, $V = -400$ V, $Q_f = 1e11$ cm⁻², $T = 293$ K
- ❑ MIP @ pixel 1:
 - Equal collected charges between isolation methods
 - Charge sharing = 0
- ❑ MIP @ center:
 - Charge loss 4% higher for p-stop with $N_{ps} = 5e16$ cm⁻³, $d=1.5$ μm

CONCLUSIONS:

- ❑ Normal with p-stop: Lowest V_{bd} , highest charge loss @ center injection
- ❑ Wide with p-spray: Highest V_{bd} , 1.3% charge loss @ center injection

